

NC273LT



Solder plus Support

No Clean Solder Paste

ENGINEERED FOR LOW TEMP APPLICATIONS



KEY FEATURES

- Used for low or reduced temperature applications
- RoHS compliant
- Improved wetting performance for bismuth alloys
- Minimizes solder balling
- 8+ hour stencil life
- Reduced component warpage
- Lower energy consumption

AVAILABILITY

NC273LT is available in multiple bismuth bearing alloys.

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NC273LT no clean, low temperature solder paste was developed with a revolutionary activator system designed to improve the wetting performance of high bismuth alloys. This unique formulation is engineered for use in low and reduced temperature applications, without compromising print performance. NC273LT is RoHS compliant, provides long stencil life, excellent transfer efficiencies and minimizes solder balling defects common to high bismuth alloys. Bismuth bearing solder pastes reduce peak reflow temperature requirements to as low as 170°C-185°C (338°F-365°F).

➤ **NC273LT** Less is More.

Contact your AIM Representative to request your free sample today.

